503382715 07/08/2015

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 EPAS ID: PAT3429337 Stylesheet Version v1.2

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JUI-LIN CHEN	06/29/2015
FENG-MING CHANG	06/29/2015
HUAI-YING HUANG	06/30/2015
PING-WEI WANG	06/30/2015

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14688321

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: T5057-1145

NAME OF SUBMITTER: RANDY A. NORANBROCK

SIGNATURE: /Randy A. Noranbrock/

DATE SIGNED: 07/08/2015

Total Attachments: 1

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PATENT REEL: 036022 FRAME: 0390 jloherm 2015/07/02 05:12:32 jloherm 2015/06/29 17:35:01

> Docket No. P20141266US00 T5057-1145

ASSIGNMENT

In consideration of the premises and other good and which is hereby acknowledged, the undersigned,	valuable consideration in hand paid, the receipt and sufficiency of
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Jui-Lin CHEN
 Huai-Ying HUANG
 Feng-Ming CHANG
 Ping-Wei WANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd, VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

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<u>IVI E I</u>	MORY DEVICE LAYOUT, SEMICONDUCTOR DEVI	CE, AND METHO	D OF
	NUFACTURING MEMORY DEVICE		
(a)	for which an application for United States Letters Patent was filed on _ United States Patent Application No. $\underline{14/688,321}$	2015-04-16	
		; or	, and identified by
(b)	for which an application for United States Letters Patent was executed	i on,	
contir Prope	ne undersigned hereby authorizes and requests the United States Commis- nited States Letters Patent which may be granted therefore and any and a mustions-in-part thereof, and the right to all benefits under the Interna- rty to the said ASSIGNEE, for its interest as ASSIGNEE, its successors as that the attorneys of record in said application shall hereafter act on behalf	all extensions, divisions, tional, Convention for the assigns and legal representations.	reissues, continuations, or
applic ASSI	AND the undersigned hereby agrees to transfer a like interest, a sation for and obtaining original, divisional, reissued or extended Letters I GNEE, its successors, assigns and legal representatives, and without furtivations for patent based thereon, growing out of or related to the said GNEE, its successors, assigns and legal representatives, deemed essential vention hereby transferred.	Patent of the United States her remuneration, in and to invention; and to execut	s, upon request of the said to any improvements, and
SIGN	ED on the date indicated aside my signature:		
1) Nan	Jai - Lin Chen 20 Date Date Date Date Date Date Date Date	015/06/29 le:	
2) Nan	1-cry - cry Chry ne: Feng-Ming CHANG Day	2015/06/24	2

PATENT REEL: 036022 FRAME: 0391

RECORDED: 07/08/2015